

PNP Darlington transistors**BSP60; BSP61; BSP62****FEATURES**

- High current (max. 0.5 A)
- Low voltage (max. 80 V)
- Integrated diode and resistor.

APPLICATIONS

- Industrial switching applications such as:
 - Print hammer
 - Solenoid
 - Relay and lamp drivers.

DESCRIPTION

PNP Darlington transistor in a SOT223 plastic package.
NPN complements: BSP50, BSP51 and BSP52.

PINNING

PIN	DESCRIPTION
1	base
2,4	collector
3	emitter

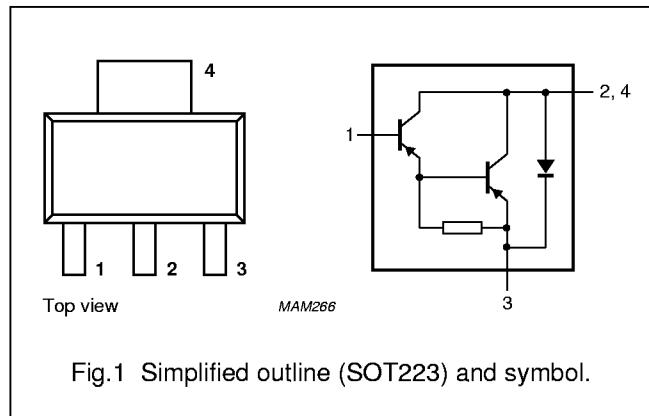


Fig.1 Simplified outline (SOT223) and symbol.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage BSP60 BSP61 BSP62	open emitter	– – –	–60 –80 –90	V
V_{CES}	collector-emitter voltage BSP60 BSP61 BSP62	$V_{BE} = 0$	– – –	–45 –60 –80	V
V_{EBO}	emitter-base voltage	open collector	–	–5	V
I_C	collector current (DC)		–	–0.5	A
I_{CM}	peak collector current		–	–1.5	A
I_B	base current (DC)		–	–100	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25^\circ\text{C}$; note 1	–	1.25	W
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	150	°C
T_{amb}	operating ambient temperature		–65	+150	°C

Note

1. Device mounted on a printed-circuit board, single sided copper, tinplated, mounting pad for collector 1 cm².
For other mounting conditions, see "Thermal considerations for the SOT223 in the General Part of associated Handbook".

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THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-a}$	thermal resistance from junction to ambient	note 1	98	K/W
$R_{th\ j-s}$	thermal resistance from junction to solder point		17	K/W

Note

1. Device mounted on a printed-circuit board, single sided copper, tinplated, mounting pad for collector 1 cm².
For other mounting conditions, see "Thermal considerations for the SOT223 in the General Part of associated Handbook".

CHARACTERISTICS $T_j = 25^\circ\text{C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{CES}	collector cut-off current BSP60	$V_{BE} = 0$; $V_{CE} = -45\text{ V}$	—	—	-50	nA
	BSP61	$V_{BE} = 0$; $V_{CE} = -60\text{ V}$	—	—	-50	nA
	BSP62	$V_{BE} = 0$; $V_{CE} = -80\text{ V}$	—	—	-50	nA
I_{EBO}	emitter cut-off current	$I_C = 0$; $V_{EB} = -4\text{ V}$	—	—	-50	nA
h_{FE}	DC current gain	$V_{CE} = -10\text{ V}$; note 1; see Fig.2	1000	—	—	
		$I_C = -150\text{ mA}$				
		$I_C = -500\text{ mA}$	2000	—	—	
V_{CEsat}	collector-emitter saturation voltage	$I_C = -500\text{ mA}$; $I_B = -0.5\text{ mA}$	—	—	-1.3	V
		$I_C = -500\text{ mA}$; $I_B = -0.5\text{ mA}$; $T_j = 150^\circ\text{C}$	—	—	-1.3	V
V_{BEsat}	base-emitter saturation voltage	$I_C = -500\text{ mA}$; $I_B = -0.5\text{ mA}$	—	—	-1.9	V
f_T	transition frequency	$I_C = -500\text{ mA}$; $V_{CE} = -5\text{ V}$; $f = 100\text{ MHz}$	—	200	—	MHz
Switching times (between 10% and 90% levels); see Fig.3						
t_{on}	turn-on time	$I_{Con} = -500\text{ mA}$; $I_{Bon} = -0.5\text{ mA}$; $I_{Boff} = 0.5\text{ mA}$	—	400	—	ns
t_{off}	turn-off time		—	1500	—	ns

Note

1. Pulse test: $t_p \leq 300\text{ }\mu\text{s}$; $\delta \leq 0.02$.

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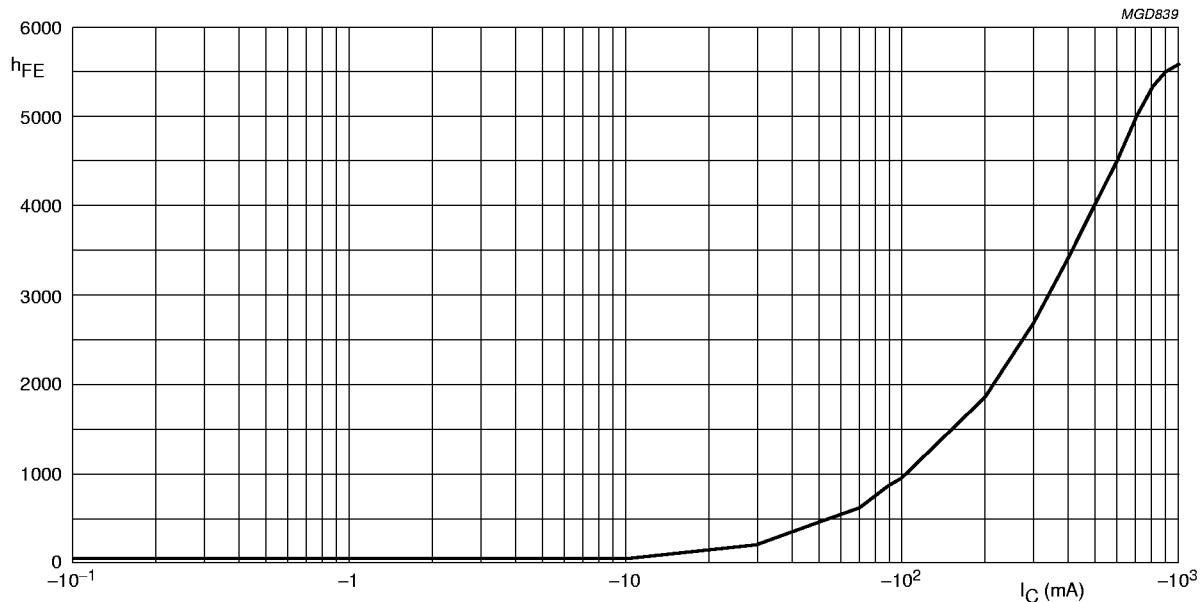
 $V_{CE} = -10$ V.

Fig.2 DC current gain; typical values.

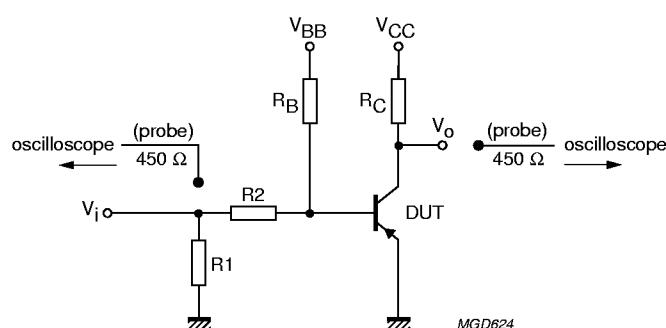
 $V_i = -10$ V; $T = 200 \mu\text{s}$; $t_p = 6 \mu\text{s}$; $t_r = t_f \leq 3 \text{ ns}$. $R_1 = 56 \Omega$; $R_2 = 10 \text{ k}\Omega$; $R_B = 10 \text{ k}\Omega$; $R_C = 18 \Omega$. $V_{BB} = 1.8$ V; $V_{CC} = -10.7$ V.Oscilloscope: input impedance $Z_i = 50 \Omega$.

Fig.3 Test circuit for switching times.

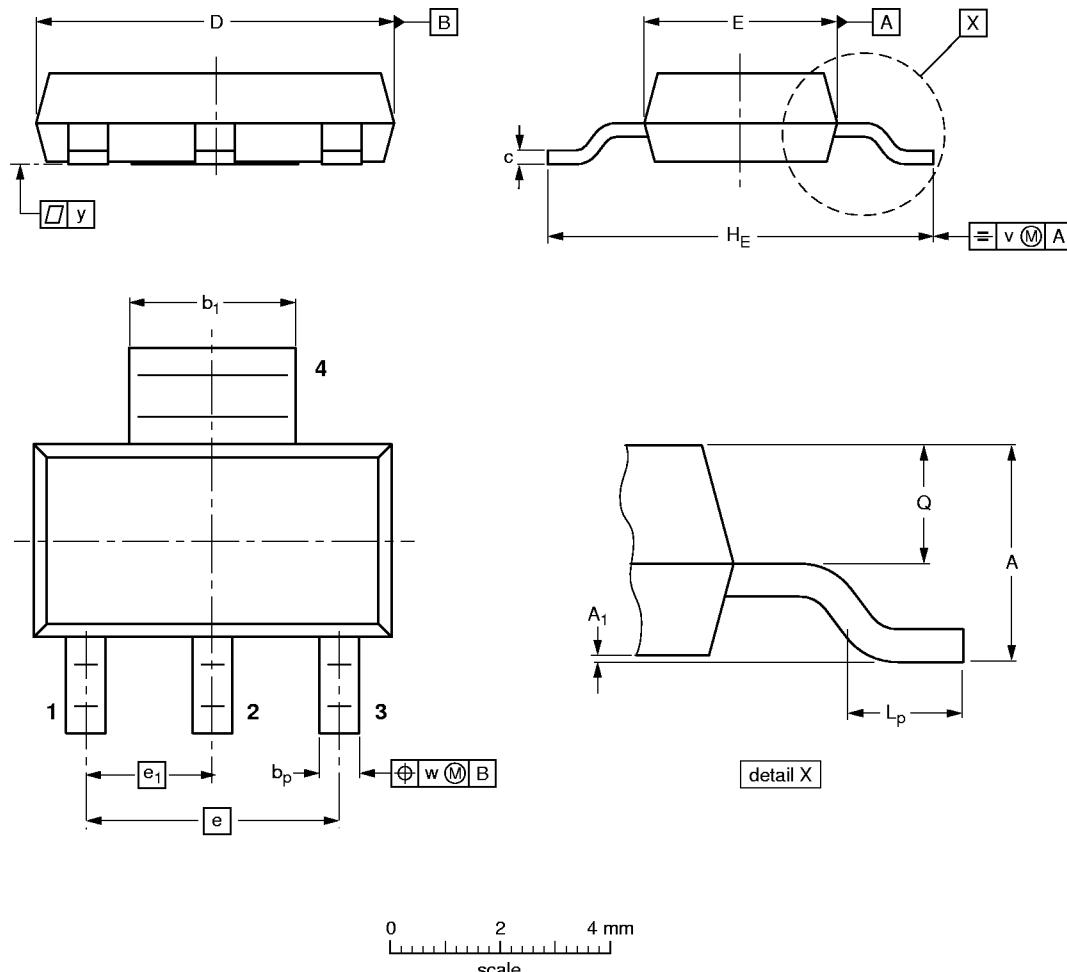
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PACKAGE OUTLINE

Plastic surface mounted package; collector pad for good heat transfer; 4 leads

SOT223



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1	b_p	b_1	c	D	E	e	e_1	H_E	L_p	Q	v	w	y
mm	1.8	0.10	0.80	3.1	0.32	6.7	3.7	4.6	2.3	7.3	1.1	0.95	0.2	0.1	0.1
	1.5	0.01	0.60	2.9	0.22	6.3	3.3			6.7	0.7	0.85			

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT223						96-11-11 97-02-28